

ABSTRACT OF THE DISCLOSURE

A circuit carrier is provided. The circuit carrier comprises a substrate, a patterned circuit layer, and a solder mask layer. The patterned circuit layer is deposited on a surface
5 of the substrate and has two passive component electrode pads. The solder mask layer covers the surface of the substrate, and includes a first solder mask opening, a second solder mask opening, and a third solder mask opening. The first solder mask opening and the second solder mask opening expose the passive component electrode pads respectively. The third solder mask opening along its length direction is divided into a
10 central area and two extension areas. The central area is between the first and the second solder mask openings. The extension areas are extending from the central area along the length direction to two sides, respectively. The width of the central area is smaller than the width of one the extension areas.